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PATENT NUMBER and ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10084563	FILING DATE 02/26/2002	CLASS 438	SUBCLASS 687	GAU 2812	EXAMINER			
10084583 02/28/2002 438 6.8.2 28/12								
PG-PUB DO NO			RESCIN					
Foreign priority claimed ☐ yes ☐ no ATTORNEY DOCKET NO								
35 USC 119 conditions met ☐ yes ☐ no Verified and Acknowledged Examiners's initials P1410								
TITLE: Method of reducing electromigration by forming an electroplated copper-zinc interconnect and								
a semiconductor device thereby formed								

NOTICE OF ALLOWANCE MAILED		T	CLAIMS ALLOWED				
		Assistant Examiner	Total Claims		Print Claim for O.G		
			DRAWING				
ISSUE FEE			Sheets Drwg.	Figs.Drwg.	Print F		
Amount Due	Date Paid	1			1		
		Primary Examined					
TERMINAL DISCLAMER		PREPARED FOR ISSUE	Application Examiner				
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		FILED WITH: DIS	K (CRF)		CD-RC		